

CLAIMS:

1. A silicone rubber adhesive composition comprising
(A) 100 parts by weight of a heat curable organopoly-
5 siloxane composition,
(B) 1 to 100 parts by weight of reinforcing silica
fines, and
(C) 0.1 to 50 parts by weight of an organic compound
or organosilicon compound having an epoxy equivalent of 100
10 to 5,000 g/mol and containing at least one aromatic ring in
a molecule.

2. The composition of claim 1 wherein component (C) is an
organosilicon compound containing at least one Si-H group in
15 a molecule.

3. The composition of claim 1 which provides a greater
bond strength to organic resins than to metals.

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20 4. An integrally molded article comprising a silicone
rubber adhesive composition in the cured state and a
thermoplastic resin, said silicone rubber adhesive
composition comprising
(A) 100 parts by weight of a heat curable organopoly-
25 siloxane composition,
(B) 1 to 100 parts by weight of reinforcing silica
fines, and
(C) 0.1 to 50 parts by weight of an organic compound
or organosilicon compound having an epoxy equivalent of 100
30 to 5,000 g/mol and containing at least one aromatic ring in
a molecule.

35 5. The integrally molded article of claim 4 wherein
component (C) is an organosilicon compound containing at
least one Si-H group in a molecule.